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PATENT APPLICATION

**RESPONSE UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER ART UNIT 2872**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akihiro MURATA et al.

GJB
9/17/03

Group Art Unit: 2872

Application No.: 09/509,669

Examiner: A. AMARI

Filed: April 4, 2000

Docket No.: 105895

For: OPTICAL MODULE

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REQUEST FOR RECONSIDERATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reply to the Office Action mailed June 16, 2003, reconsideration is requested based on the following remarks.

Claims 1-12 and 16-18 are pending. Reconsideration in view of the following remarks is respectfully requested.

I. The Claims Define Patentable Subject Matter

The Office Action rejects claims 1-4 and 16-18 under 35 U.S.C. §102(b) as anticipated by Hayashi "An Innovative Bonding Technique for Optical Chips using Solder Bumps that Eliminate Chip Positioning Adjustments"; and claims 5-12 are rejected under 35 U.S.C. §103(a) as unpatentable over Hayashi in view of U.S. Patent No. 5,940,550 to Plickert et al. These rejections are respectfully traversed.

The applied art does not disclose a mounting member having a principle surface with a mounting member made of glass and having a core and cladding, with the cladding having its surface to form the principle surface in whole, and the mounting member is an optical waveguide for guiding light, as claimed in claim 1 and similarly claimed in claims 4, 17 and 18.

Instead, Hayashi discloses an optical waveguide on a mounting member with a groove formed in the mounting member. Thus, the waveguide forms only a portion of the principle surface.

Further, Hayashi discloses on page 226, lines 19-23 that a technique is needed to reduce the complexity of coupling between optical waveguides on the boards and optical fibers. It has already been demonstrated that the solder bump technique, in combination with a precision V-groove technique, can solve this problem. As such, Hayashi inherently teaches positioning an optical fiber in a V-groove, but does not imply that the core is a section formed in the mounting member by doping the section. Accordingly, the present invention is not anticipated by Hayashi and Hayashi cannot support a §102 rejection.

For at least the reasons discussed above, it is respectfully submitted that claims 1, 4, 17 and 18 are distinguishable over the applied art. Withdrawal of the rejections under 35 U.S.C. §102 and §103 is respectfully requested.

II. Conclusion

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of the claims are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,


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Date: September 11, 2003

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